MATERIAL DECLARATION SHEET

Material Number	CD1005-TxxC Series		
Product Line	Semiconductor Products		
Compliance Date	**2007/9/28**		
RoHS Compliant	**YES**	MSL	**1**

No.	Construction Element (subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	FR-4 Board	Substrate/ Terminal	2.716	Copper	7440-50-8	27.62%	0.750	41.47
				Nickel	7440-02-0	4.244%	0.115	
				Gold	7440-57-5	0.140%	0.004	
				Epoxy resin	65997-17-3	68.00%	1.847	
2	Wafer	Diode	0.057	Silicon	7440-21-3	94.21%	0.055831	0.87
				Aluminum	7429-90-5	0.44%	0.001140	
				Titanium	7440-32-6	0.08%	0.000001	
				Gold	7440-57-5	5.20%	0.000001	
				Arsenic	7440-38-2	0.07%	0.000027	
3	Al wire	Conductor	0.002	Aluminum	7429-90-5	99%	0.00198	0.03
				Silicon	7440-21-3	1%	0.00002	
4	Silver paste	Welding	0.012	Modified Epoxy Resin	29690-82-2	16%	0.00192	0.18
				Silver	7440-22-4	80%	0.0096	
				Imidazole	827-43-0	2%	0.00024	
				Dicyandiamide	461-58-5	2%	0.00024	
5	Molding Compound	Outer	3.762	Silica	60676-86-0	80.00%	3.010	57.45
				Epoxy Resin	29690-82-2	10.00%	0.376	
				Phenolic Resin	9003-35-4	9.50%	0.357	
				Carbon Black	1333-86-4	0.50%	0.019	
		Total weight	6.549					

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This Document was updated on: 2015/11/30

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.

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